Press

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SMT Hybrid Packaging 2018
International Exhibition and Conference
for System Integration in Micro Electronics
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Update: SMT Hybrid Packaging 2018

With a growth of seven percent compared to the prior year, 80 percent of space at the SMT Hybrid Packaging 18 has already been booked. As Europe´s leading platform for system integration in microelectronics, the SMT Hybrid Packaging is the ideal platform for companies to present their products and solutions – from the initial idea and its development, to the production of all technical processes during the manufacturing of electronic assemblies.

Special offer for new exhibitors – available once again in 2018

As a result of the positive feedback given on “Newcomer Pavilion”, the joint stand will again be organized in 2018. First-time exhibitors can benefit from a special offer allowing companies to cost-efficiently test the SMT Hybrid Packaging, with low organizational effort. Newcomer G-SMT Hungary confirms: “We are full of satisfaction. It was a great organization and it was a great place for the Newcomer Pavilion.”

Further attractive joint stands and special interest area

In addition to the Newcomer Pavilion, the Fair will hosting further exciting joint stands, as well as a special interest area.

PCB meets Components
PCBs, components and materials focusing on one area: the mixed double “PCB meets Components” incorporates the advancement of the proven High Tech PCB Area und brings together producers of PCBs and corresponding components.

Companies can participate individually or with a complete stand package on this special interest area.

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EMS-Intersection

The joint stand EMS-Intersection offers a thematically-fitting platform for contract manufacturers from the areas of electronic production, SMT assembly (THT), PCB assembly, electronic design and development (hardware and software), final assembly of complete electronic appliances, modules and systems, electrical and optical tests as well as repair services.

During the last event, exhibitors especially appreciated the possibility of participating with a small booth as from 6 square meters. This offer is available once again for 2018.

Optics meets Electronics

Products and solutions on the topic optoelectronics are shown by exhibitors on the joint stand “Optics meets Electronics”. The focus resulted in positive feedback from participating companies last time around: “Even as a newcomer to the industry, it was possible for us to gain high quality contacts”* said Axel Graf from Optimum datamanagement solutions GmbH.

Stand spaces still available

With its extensive possibilities and offerings, the SMT Hybrid Packaging 2018 is the ideal event in the area of microelectronics. Companies can receive information and request application documents at smthybridpackaging.com.

About Mesago

Mesago Messe Frankfurt GmbH, founded in 1982 and located in Stuttgart, specializes in exhibitions and conferences on various topics of technology. The company belongs to the Messe Frankfurt Group. Mesago operates internationally and is not tied to a specific venue. With 130 members of staff Mesago organizes events for the benefit of more than 3,300 exhibitors and over 110,000 trade visitors, conference delegates and speakers from all over the world. Numerous trade associations, publishing houses, scientific institutes and universities work with Mesago closely as advisers, co-organizers and partners. (mesago.com)

*translated from German